



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D

*\* : Required Field*

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2016-06-20
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	Laurent TOSI	<b>Representative Title</b>	MMS MD CHAMPION
<b>Representative Phone *</b>	33 442 685 795	<b>Representative Email *</b>	<a href="mailto:laurent.tosi@st.com">laurent.tosi@st.com</a>
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**


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Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32F072C8U6TR	B2MI*448XXXY	A	9988	2016-06-20
	Amount	UoM	Unit type	ST ECOPACK Grade
	99.700	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant ( in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used or other bulk termination : add in comments	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFN	7x7x0.55	48	L bend	
Comment	Package: UFQFPN 7X7X0.55 48L0.5 MM PITCH			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	<b>true</b>
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	Description

Query : California Prop65 list, dated 14 August 2015			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			<b>FALSE</b>
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			<b>TRUE</b>
Substance	amount in product (mg)	Application	ppm in product
Nickel	1.96	Plating underlayer	19659

QueryList : REACH-20th June 2016				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				<b>true</b>
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	B2MI*448XXXY					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	4.108	mg	supplier	die	Silicon (Si)	7440-21-3		3.639	mg	885833	36499
Die				supplier	metallization	Aluminium (Al)	7429-90-5		0.027	mg	6573	271
Die				supplier	metallization	Copper (Cu)	7440-50-8		0.134	mg	32619	1344
Die				supplier	metallization	Cobalt (Co)	7440-48-4		0.025	mg	6086	251
Die				supplier	metallization	Titanium (Ti)	7440-32-6		0.007	mg	1704	70
Die				supplier	metallization	Tungsten (W)	7440-33-7		0.015	mg	3651	150
Die				supplier	Passivation	Silicon Nitride	12033-89-5		0.018	mg	4382	181
Die				supplier	Passivation	Silicon Oxide	7631-86-9		0.169	mg	41139	1695
Die				supplier	polymer die coating	PIX1 Gamma-butyrolactone	96-48-0		0.074	mg	18014	742
Die Attach	Other inorganic materials	0.435	mg	Supplier	Epoxy	Silver	7440-22-4		0.307	mg	705747	3079
Die Attach				Supplier	Epoxy	Bisphenol-F, epoxy resin	9003-36-5		0.021	mg	48276	211
Die Attach				Supplier	Epoxy	Fatty acids, polymers with epichlorohydrin	68475-94-5		0.021	mg	48276	211
Die Attach				Supplier	Epoxy	Gamma Butyrolactone	96-48-0		0.021	mg	48276	211
Die Attach				Supplier	Epoxy	Epoxy Resin Proprietary	Properties		0.021	mg	48276	211
Die Attach				Supplier	Epoxy	Poly(Oxy(methyl-1, 2-ethanediyl)	9046-10-0		0.021	mg	48276	211
Die Attach				Supplier	Epoxy	Copper Oxide	1317-38-0		0.021	mg	48276	211
Die Attach				Supplier	Epoxy	1,4-Bis(2,3-epoxypropoxy) butane	2425-79-8		0.002	mg	4598	20
Encapsulation	Other inorganic materials	34.983	mg	Supplier	Molding compound	Epoxy Resin A	Proprietary		1.107	mg	31644	11103
Encapsulation				Supplier	Molding compound	Epoxy Resin B	Proprietary		1.107	mg	31644	11103
Encapsulation				Supplier	Molding compound	Phenol Resin A	Proprietary		1.107	mg	31644	11103
Encapsulation				Supplier	Molding compound	Phenol Resin B	Proprietary		1.107	mg	31644	11103
Encapsulation				Supplier	Molding compound	Metal Hydroxide	Proprietary		0.553	mg	15808	5547
Encapsulation				Supplier	Molding compound	Carbon Black	1333-86-4		0.111	mg	3173	1113
Encapsulation				Supplier	Molding compound	Silica Fused	60676-86-0		29.891	mg	854444	299809
Wire	Other inorganic materials	0.666	mg	Supplier	Wire	Gold	7440-57-5		0.666	mg	999385	6680
Wire				Supplier	Wire	Palladium	7440-05-3		0.000	mg	600	4
Wire				Supplier	Wire	Lanthanum	7439-91-0		0.000	mg	15	0
Finishing	Other inorganic materials	3.083	mg	Supplier	Connection coating	Tin	7440-31-5		3.083	mg	1000000	30923
Leadframe	Other inorganic materials	56.425	mg	Supplier	Alloy	Copper	7440-50-8		53.008	mg	939441	531671
Leadframe				Supplier	Alloy	Nickel	7440-57-5		1.960	mg	34737	19659
Leadframe				Supplier	Alloy	Silicon	7440-21-3		0.424	mg	7514	4253
Leadframe				Supplier	Alloy	Magnesium	7440-50-8		0.099	mg	1755	993
Leadframe				Supplier	Coating	Silver	7440-22-4		0.934	mg	16553	9368